

Technical Data Sheet

MODEL NO: Q150OVS4 1206Package 3.2*1.6mm Chip LEDs

Features:

• Package in 8mm tape on 7" diameter reel

• Compatible with automatic placement equipment

• Compatible with reflow solder process

Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP/GaAs	Red	Water Clear

Electrical/Optical Characteristics(Ta= 25° C)

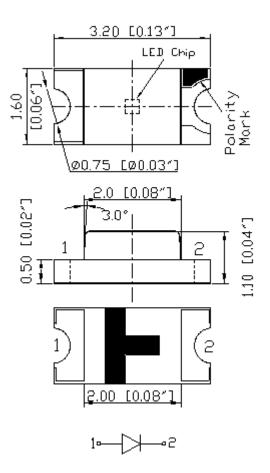
Parameter	Test	Symbol	Value			Unit
	Condition		Min	Тур	Max	Unit
Spectral half bandwidth	IF=20mA	Δλ		17		nm
Dominant wavelength	IF=20mA	λD	615	620	630	nm
Forward voltage	IF=20mA	VF	1.7	2.0	2.5	V
Luminous intensity	IF=20mA	lv		600		mcd
Viewing angle at 50% lv	IF=10mA	2 <i>0</i> 1/2		140		Deg
Reverse current	V _R =5V	lR			10	μА

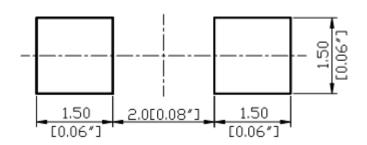


Absolute Maximum Ratings(Ta=25 $^{\circ}$ C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	75	mW
Forward current	lF	30	mA
Reverse voltage	VR	5	V
Operating temperature range	Тор	-40 ~+80	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+85	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/8 duty f=1kHz)	IFP	125	mA

PACKAGING DIMENSIONS (mm):





Precautions For Use:

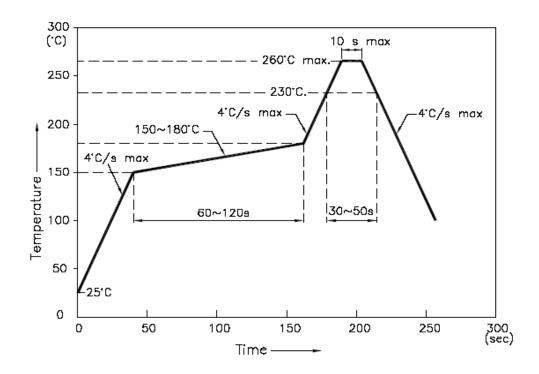
Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

- 1. The operation of temperature and R.H. are : 5° C $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C}\pm5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time



NOTES:

- 1. We recommend the reflow temperature $245^{\circ}\mathbb{C}(\pm 5^{\circ}\mathbb{C})$. the maximum soldering temperature should be limited to $260^{\circ}\mathbb{C}$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

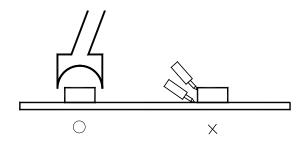


■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

■Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \, solder etc.